Securing the U.S. Electronics Supply Chain



PROGRAM MANAGER: Mr. Michael Sangillo / MTO

DATE: Thursday, August 24, 2023	TIME: 12:30pm-3:30pm
ROOM NAME: Columbia D – 3 rd Floor	

DESCRIPTION:

The world-wide microchip meltdown of 2022 occurred due to temporary shutdowns in material sourcing, component supplier, and distribution chains. Although these shutdowns were temporary, they had enduring effects on the economy. This workshop will explore the ramifications of a weakened supply chain and will offer new technology concepts that strengthen the U.S. electronics supply chain.

AGENDA

12.20pm 12.45pm	Introductions Drief on supply chain sequenty
12:30pm-12:45pm	Introductions – Brief on supply chain security
	Mr. Michael Sangillo, Program Manager, DARPA
12:45pm-1:15pm	Supply network analytics and forecasting for vulnerability mitigation
	Mr. Trevor Stansberry, President, Exiger
1:15pm-1:45pm	Accelerating the U.S. strategic advantage of advanced microelectronics packaging and
	manufacturing
	Dr. Darren Crum, R&E Advanced Packaging Lead/SOTA Heterogenous Integrated
	Packaging (SHIP) Digital Technical Manager, U.S. Navy
Afternoon Break: 1:45pm-2:15pm	
2:15pm-2:45pm	Material veracity and secure digital ledger innovation
Dr. Nicholas D. Pattengale, Distinguished Member of Technical Staff, Sandia National	
	Laboratories
2:45pm-3:15pm	Semiconductor supply chain affecting computer architecture (DRAFT TITLE)
	Mr. David Wentzlaff, Associate Professor, Department of Electrical and Computer
	Engineering, Princeton University
3:15pm-3:30pm	Speaker Panel Q/A Session
Workshop Concludes at 3:30pm	